



Material Content Data Sheet



Sales Product Name		IPD079N06L3 G		Issued		27. September 2017		
MA#		MA000471074						
Package		PG-TO252-3-311		Weight*		314.02 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.120	0.68	0.68	6751	6751
leadframe	non noble metal	iron	7439-89-6	0.143	0.05		456	
	inorganic material	phosphorus	7723-14-0	0.043	0.01		137	
	non noble metal	copper	7440-50-8	143.098	45.56	45.62	455700	456293
wire	non noble metal	aluminium	7429-90-5	2.113	0.67	0.67	6730	6730
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.978	0.63		6300	
	plastics	brominated resin	-	2.119	0.68		6750	
	organic material	carbon black	1333-86-4	2.261	0.72		7200	
	plastics	epoxy resin	-	19.075	6.07		60746	
	inorganic material	silicondioxide	60676-86-0	115.865	36.90	45.00	368977	449973
leadfinish	non noble metal	tin	7440-31-5	3.740	1.19	1.19	11910	11910
plating	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	275	276
	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
solder	noble metal	silver	7440-22-4	0.054	0.02		173	
	non noble metal	tin	7440-31-5	0.043	0.01		138	
	non noble metal	lead	7439-92-1	2.074	0.66	0.69	6606	6917
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		61	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	copper	7440-50-8	19.177	6.11	6.12	61071	61150
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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